

MINIPIX TPX3

Datasheet

Model No.:

MNXT3S-Xxx190411 MNXT3S-Xxx190925





General features

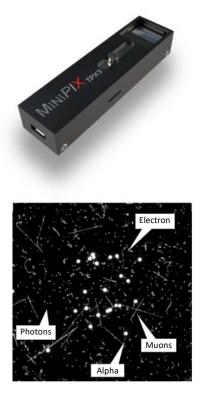


Illustration of particle tracking capability of Timepix3 device: The tracks of different particles of radiation background were recorded during 10 minutes in office space in Prague. Brightness corresponds to energy. No noise (clean zero) is seen in dark regions. All basic particle track types are seen nicely: muons = straight lines, alpha particles = bright balls, electrons = curving lines, gamma and X-rays = dots and blobs. The **MINIPIX**_{TPX3} is a miniaturized and low power radiation camera equipped with particle tracking and imaging detector Timepix3 (256 x 256 square pixels with pitch of 55 μ m). Several sensor materials are provided according to customer preference (usually 300 μ m thick silicon).

The Timepix3 detector is position, energy and time sensitive: For each ionizing particle (e.g. X-ray photon) it digitally registers its position, energy, time of arrival and track shape - basically all information you can want. The other measures can be calculated from the track shape (particle type, direction of flight, LET, charge ...). The information on each detected particle is either read-out immediately (pixel mode) at maximal rate of 2.3 million hit pixels per second (pixel mode) or accumulated in images (frame mode) and read-out later at maximal speed of 16 frames per second.

The typical and intended applications of MINIPIX TPX3 are:

- Spectral X-ray imaging: X-ray fluorescence imaging, X-ray radiography (low flux).
- Energy dispersive XRD, SAXS or WAXS: Monochromatic X-ray source is NOT needed! Even high energy for thick samples is possible (e.g. 100 keV)!
- Spectral gamma ray imaging: Scintigraphy or SPECT, radiography with isotopes.
- Radiation monitor¹: Particle type sorting, spectroscopy, directional sensitivity ...
- Gamma camera: Special shielded box and collimators are available upon request.
- **Compton camera:** Gamma ray imaging based on Compton scattering (special software module for image reconstruction is required).

The **MINIPIX**_{TPX3} device is controlled via USB2.0 interface with standard µUSB connector. The complex software PIXET PRO for detector operation is provided together with the device. All major operating systems are supported (MS Windows, Mac OS and LINUX). Extra software modules are available for special functions (e.g. spectrum filtering and reconstruction, coded aperture image reconstruction, Compton camera image and spectrum reconstruction, radiation field decomposition, networking of many devices ...).

Main Features

- Readout chip type Timepix3
- Pixel size55 x 55 μm
- Dynamic range in frame mode²..... 1022 events count
- Dark current none
- Interface USB 2.0 (High Speed)
- Maximum frame rate16 fps (full frames)
- - Weight 41 g





Device parameters

Operating conditions

Symbol	Parameter	Min	Тур.	Max	Units	Comment
TA	Temperature Range	0	25	50	°C	
Φ	Humidity	0	55	60	%	Not condensing

Electrical Specification

T_A = 25°C, USB voltage V_{CC} = 4.8V

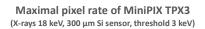
Symbol	Parameter	Min	Тур.	Max	Units	Comment
Vcc	Supply Voltage	4.0	5.0	5.5	V	Comply with USB 2.0
1	Supply Current		300	500	mA	Comply with USB 2.0,
Icc	Supply Current			300	IIIA	Mode dependent
P1	Power Dissipation			2.5	W	
Bias Voltage Sou	rce for Sensor Diode					
V _{BIAS}	Bias Voltage (positive version)	3		450	V	Max. limited internally
VBIAS	Blas voltage (positive version)			430	v	according to sensor type
VBIAS	Bias Voltage (negative version)	-4		-450	V	With CdTe or CZT sensor

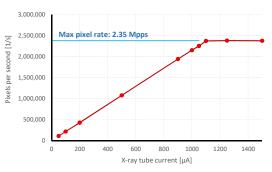
Performance characteristics

Symbol	Parameter	Min	Тур.	Max	Units	Comment
f _f	Frame-rate			16	fps	with USB 2.0 Host
TFREAD	Frame Readout Time ³	62			ms	
fp	Pixel type hit-rate in ToT+ToA mode (pixels per second)			2.35 x 10 ⁶	pps	with USB 2.0 Host

Pixel mode hit-rate measurement

The whole detector is exposed to homogenous direct (perpendicular) irradiation from X-ray tube operated at 18 kVp with 2 mm Aluminum filter. The measurement type is set to "**Pixels**" and mode to "**ToT+ToA**", all other parameters are set to factory defaults (as stored in configuration file delivered with the device). The exposure time is set to 0.1 s. The "Clustering" tool of PiXet-Pro is used to analyze measured data. The number of hit pixels per second is drawn as function of X-ray tube current searching for saturation.





¹ MINIPIX_{TPX3} is not a certified dosimetric device. It serves as the first level indicator and monitor of radiation fields allowing identification of radiation type. Radiation protection of people cannot be based on measurements of MINIPIX_{TPX3}.

³ During Readout time (or Dead time), no signal is collected from the sensor.



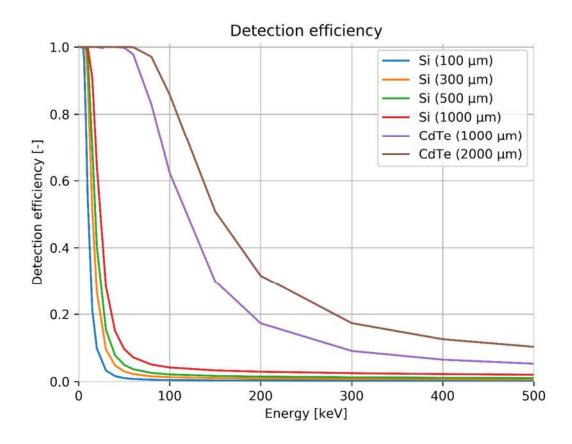
² i.e. counter depth. Dynamic range of integrated picture is theoretically unlimited. Maximal counting freq. per pixel is 1 MHz.



Sensor parameters

T_A = 25°C

Symbol	Parameter	Si			Cd	Те	Units	Comment	
	Thickness	100	300	500	1000	1000	2000	μm	
	Minimum energy threshold	2.0 - 2.7	2.0 - 2.7	2.0 - 3.0	2.0 - 3.0	2.5 - 4.5	3.0 - 5.0	keV	
σ Thl@60	Energy resolution in ToT mode ($\sigma @ 60 \text{ keV}$)	1.2 - 2.6	1.3 - 2.7	1.4 - 3.5	1.7 - 3.6	2.8 - 5.4	2.9 - 8.3	keV	
O Thl@122	Energy resolution in ToT mode (σ @ 122 keV)					3.4 - 6.0	4.5 - 9.9	keV	
	Typical detectable energy range for X-rays	2.0 - 60		2.5 - 500		keV	See chart below		
	Pixel size	55						μm	



Basic principles, measurement types and operational modes

The ionizing radiation particle interacts with the sensor material creating an electric charge. This charge is collected by electric field and brought to pixel preamplifier where it is amplified and shaped forming triangular voltage pulse. The amplitude and duration of this pulse is proportional to energy deposited by particle within the pixel. The situation when the voltage pulse amplitude in particular pixel exceeds preselected threshold value is called "event" or "hit".

Each pixel contains three digital counters (10, 14 and 4 bits). These counters are used differently according to measurement type and mode. There are four different quantities which can be measured and stored in counters of each pixel – these are selected by operational modes.



Datasheet | Device parameters



Operational modes:

operational modes	
Number of Events	= number of events (hits) in the pixel during exposure time (this mode is suitable mainly for frame type readout).
Time- o ver-Threshold (ToT)	= number of periods of 40 MHz clock signal (25 ns step) when amplifier output signal stays over the energy threshold. The ToT can be transformed to energy in keV using per-pixel-calibration function. The coefficients for per-pixel-calibration are unique for each pixel and they are stored in configuration file delivered with the device. The energy calibration is valid only for given values of other detector parameters as delivered in configuration file (especially threshold).
T ime- o f- A rrival (ToA)	= number of periods of 40 MHz clock signal (25 ns step) from start of exposure till the event is registered by pixel (i.e. pulse in pixel crosses the threshold). The range is 409.6 μ s. Additional 16 bits are added in FPGA in readout electronics so that the total range is 26.8 seconds.
F ast- T ime- o f- A rrival (FToA)	= time difference between event detection and next clock signal measured with step of 1.5625 ns. Range is 4 bits. The combination of ToA and FToA gives precise time of event detection in nanoseconds using following formula:
	Time [ns] = ToA*25 - FToA*1.5625
Measurement types:	
Frame type measurement	No data is sent out of device during the exposure time. All measured events are accumulated in counters of pixels. <i>Event counter</i> is incremented and ToT is integrated in to <i>iToT counter</i> for all events. The measured data is read-out after end of exposure time for all pixels with nonzero content. No measurement can be performed during readout process.
B ¹ 1 1	

 $\label{eq:product} Pixel type measurement \qquad \mbox{Information about all hit pixels is read-out immediately and continuously during exposure time. If hit rate is below maximal value (see f_p in table of Performance characteristics) then there is practically no deadtime. \\$

Combinations of operation modes and measurement types (rarely used cases are shown with gray background):

Туре	Mode	Range	Description
Frame (reading all pixels after	Event+iToT	10 bit + 14 bit	2 output frames per exposure: Events = number of events in pixel iToT = total time over threshold for all events in pixel
end of exposure)	iToT	14 bit	1 output frame: iToT = total time over threshold for all events in pixel
	ТоА	18 bit	1 output frame: ToA+FToA ¹ = Time of Arrival of first event in pixel
Pixel	ToT+ToA	10 bit + 18 bit	4 numbers per pixel per event: Position, ToT, ToA and FToA ¹
(reading only hit pixels continuously during	ТоА	18 bit	3 numbers per pixel per event: Position, ToA and FToA ¹
exposure)	Only ToT	10 bit	2 number per pixel per event: Position and ToT

¹ ToA and FToA are combined together by software automatically. If saved, ToA and FToA are stored as separate items (for Pixel type measurement).



Datasheet | Device description



Device description

The device is delivered with USB flash disk containing installer of PiXet-Pro software, unique device configuration and calibration file and protocol on quality test report. The device casing is made of aluminum with sliding cover made of stainless steel protecting the sensor window. The communication and powering is provided by USB 2.0 Micro-B connector and cable.

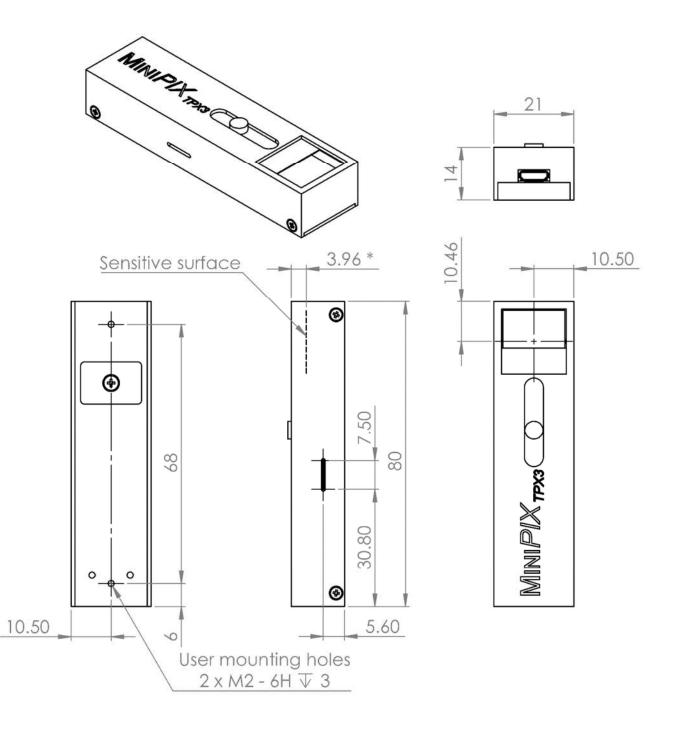


USB connector USB type Micro-B, Standard USB 2.0 High-Speed.





Mechanical dimensions



All dimensions are in mm.

* Sensitive surface distance from top of the box is stated for 300 μm sensor thickness.

Extreme care must be taken when handling $MINIPIX_{TPX3}$ without the protecting cover. Warranty does not apply to mechanical damage of the sensor and wirebonds.



Datasheet | Model Number Codes

Model Number Codes

Example:	MNX	T3S	-	x	P T	<u>3</u>	190925
Device name:							
MNX – MiniPIX							
Device modification:							
T3S – Timepix3 Standard							
Sensor type:							
P – Planar silicon							
C – CdTe							
Sensor thickness:							
1 – 100 μm							
3 – 300 μm							
5 – 500 μm							
A – 1000 μm							
B – 2000 μm							
Device version date:							

YY MM DD

Release history

Date	Changes				
19/04/12	Preliminary datasheet				
20/04/03	New version; Mechanical dimensions; Sensor parameters				



Warning

Do not touch sensor surface!

Instructions for safe use

To avoid malfunction or damage to your **MINIPIX**_{TPX3} please observe the following:

- Do not expose to water or moisture. •
- Do not disassemble. Wire-bonding connection may be irreversibly damaged.
- Do not insert any object into the sensor window.
- Maximum USB cable length is 3m. .

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